United States Patent [19]

Kies et al.

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[45] **Date of Patent: ** Sep. 30, 1986**

[54] **HOUSING FOR INTERFACE MODULE**

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[73] Assignee: **Rockwell International Corp.**, El Segundo, Calif.

[**] Term: **14 Years**

[21] Appl. No.: **561,383**

[22] Filed: **Dec. 14, 1983**

[52] **U.S. Cl.** **D14/114**; D13/41

[58] **Field of Search** D14/100, 107, 114; D13/40, 41; 174/50, 52; 361/331, 332, 380, 381, 390, 391, 392, 394

[56] **References Cited**

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[57] **CLAIM**

The ornamental design for a housing for interface module, substantially as shown and described.

DESCRIPTION

FIG. 1 is a top view of the housing for interface module, showing our new design;

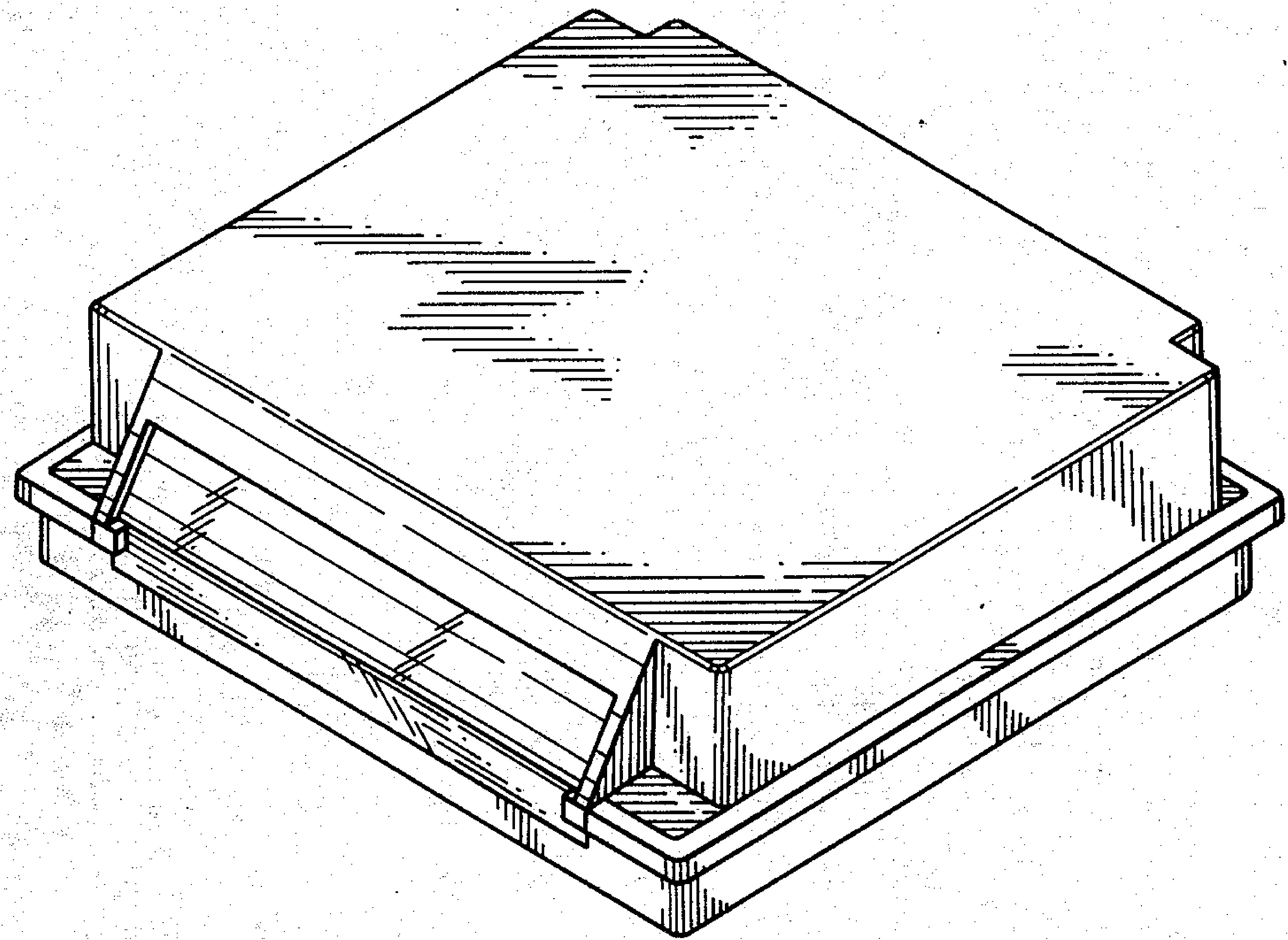
FIG. 2 is a front view thereof;

FIG. 3 is a side view thereof;

FIG. 4 is a perspective view thereof;

FIG. 5 is a view opposite that shown in FIGS. 3 and 4; and

FIG. 6 is a rear view thereof.



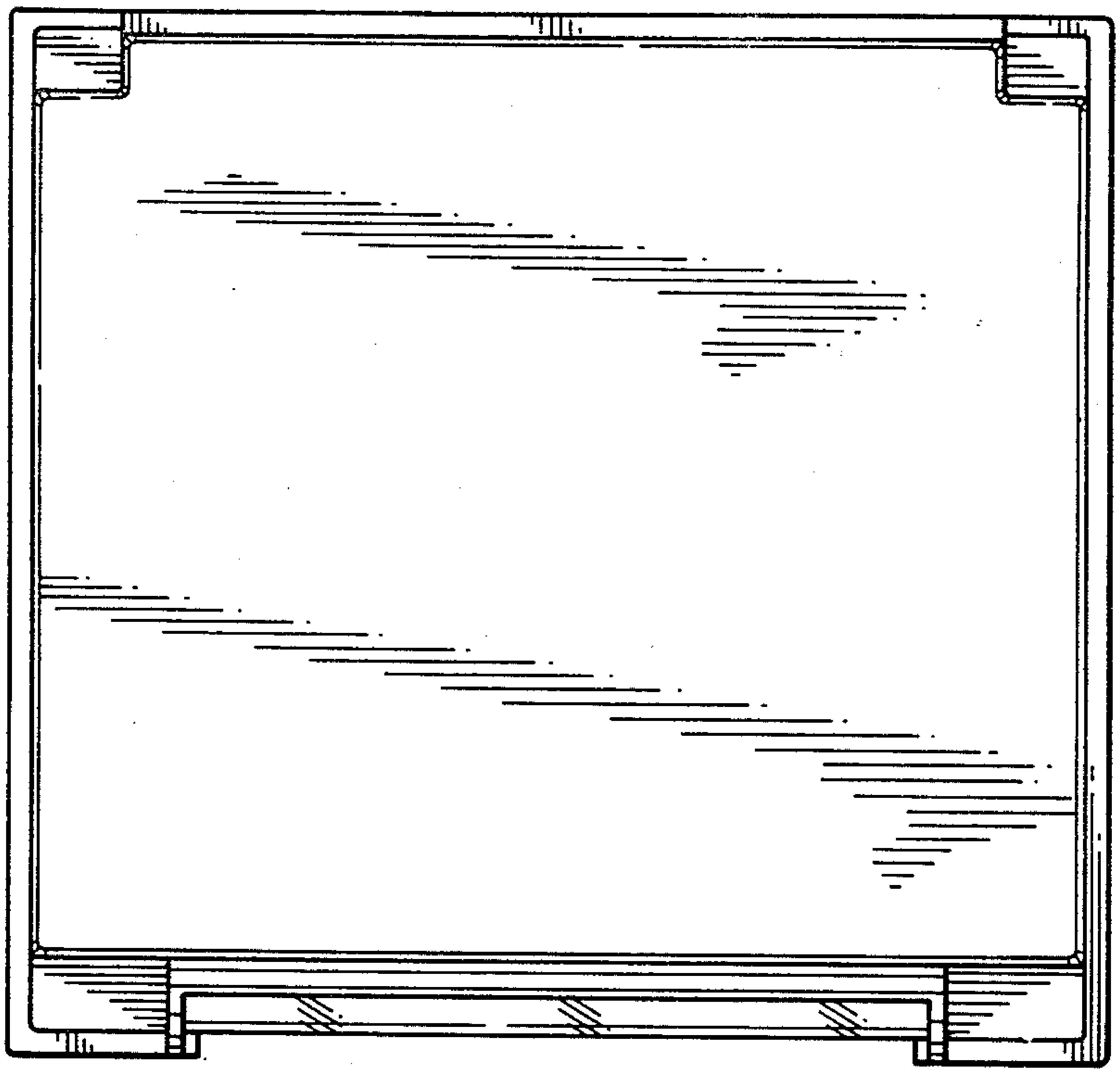


FIG. 1

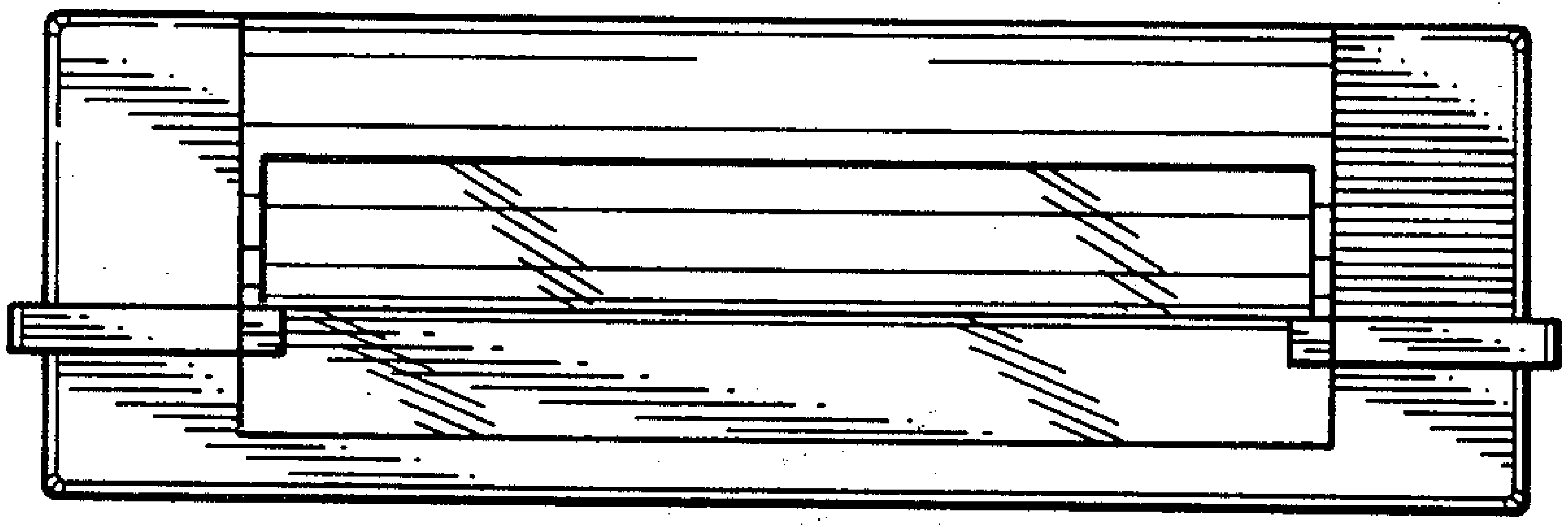


FIG. 2

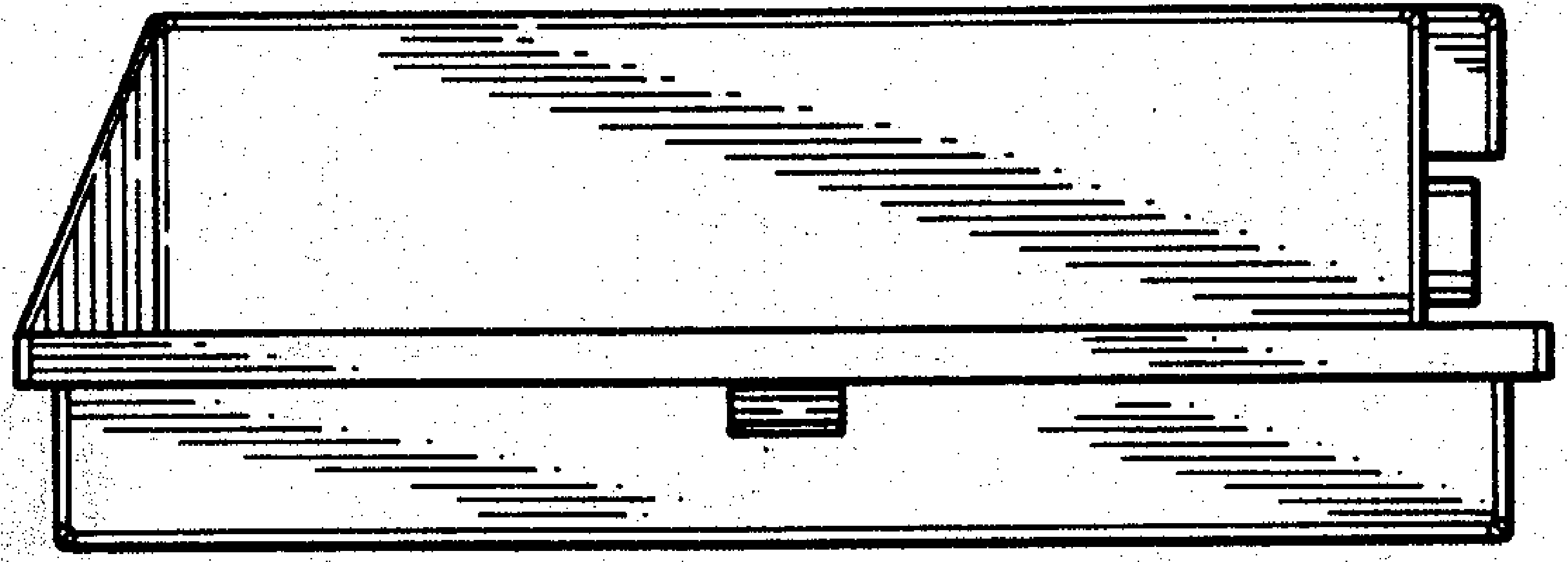


FIG. 3

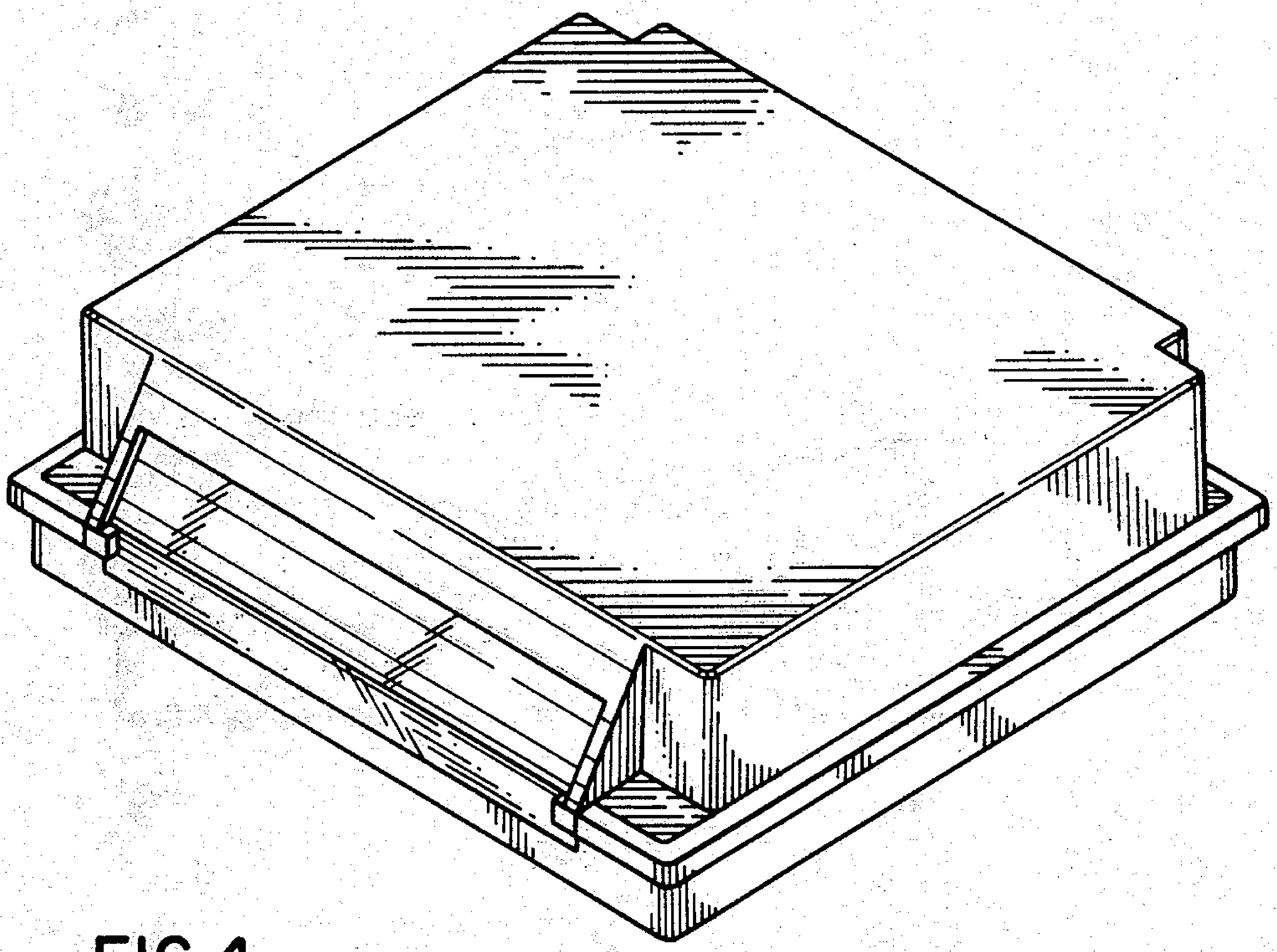


FIG. 4

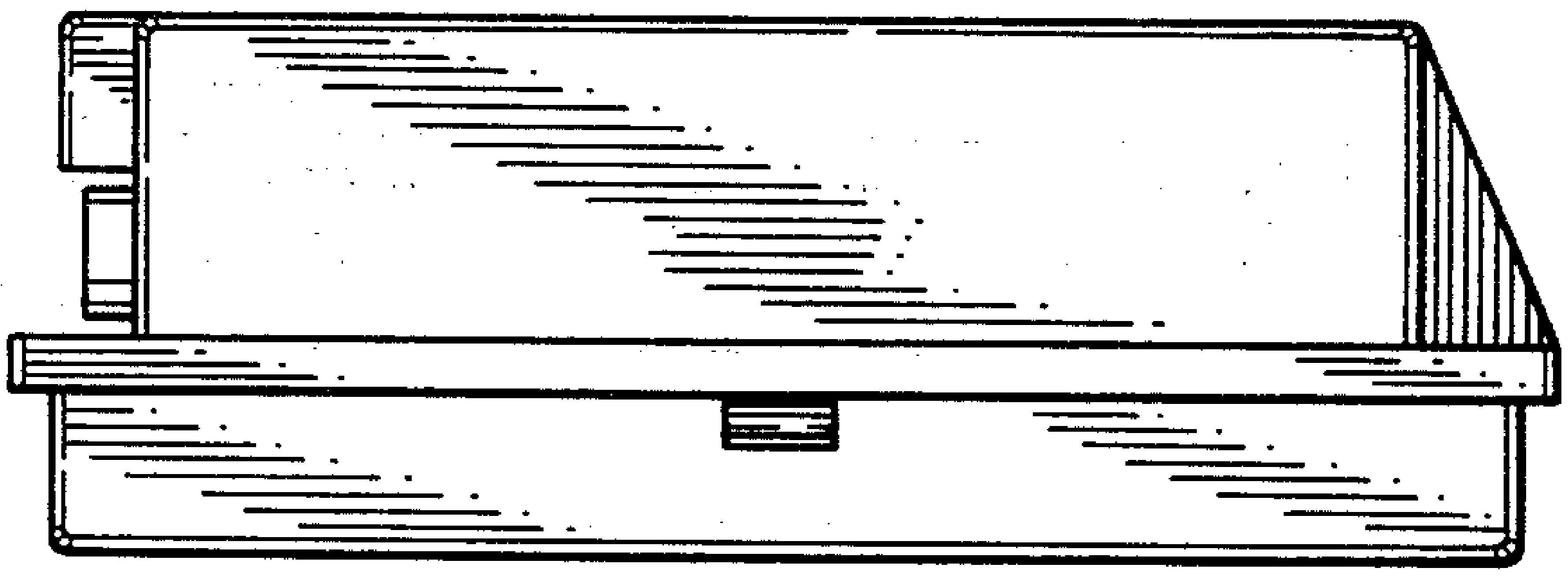


FIG. 5

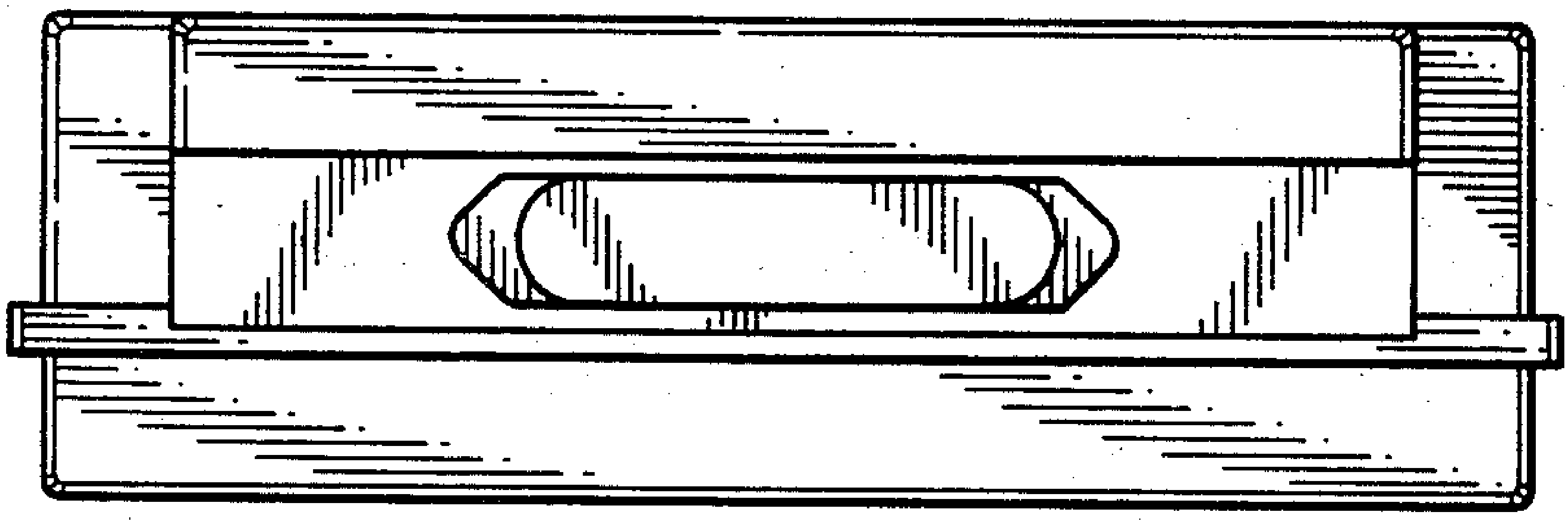


FIG. 6